09/760,741

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Docket No.: M4065.0374/P374
(PATENT)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Letters Patent of:
Jerry M. Brooks

Patent No.: 6,900,549

Issued: May 31, 2005

For: SEMICONDUCTOR ASSEMBLY WITHOUT ADHESIVE FILLETS

REQUEST FOR CERTIFICATE OF CORRECTION
PURSUANT TO 37 CFR 1.322

Attention: Certificate of Correction Branch
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

Upon reviewing the above-identified patent, Patentee noted errors which should be corrected.

In the Specification, the following errors are to be corrected:

Column 1, line 31, "it Limits" should read --it limits--; and

Column 4, lines 17-18, "above. It" should read --above. As shown in Figure 7, when the adhesive fillet 24_b is eliminated, there can be cavities 25 between each of the second and third semiconductor dies 30, 45 and between the first semiconductor die 20 and the supporting structure 10. It--.

The PTO failed to include the sentence that was inserted by Applicant in the Amendment in Response to Non-Final Office Action, filed February 25, 2004 (copy attached, in part, as Exhibit A) when printing the patent.

In Claim 9, the following is to be corrected:

Column 5, line 39, "arid" should read --and--.

The errors were not in the application as filed or amended by Applicant; accordingly no fee is required.

Transmitted herewith is a proposed Certificate of Correction effecting such amendment. Patentee respectfully solicits the granting of the requested Certificate of Correction.

Dated: January 16, 2007

Respectfully submitted,

By _____ #41,198

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Exhibit A

Atty Docket No.: M4065.0374/P374

Inventor: Mike Brooks

Application No.: 09/760,741-Conf. #5786 **Filing Date:** January 17, 2001
Title: SEMICONDUCTOR ASSEMBLY WITHOUT ADHESIVE FILLETS

Documents Filed:
Amendment Transmittal (1 page)

Amendment (25 pages)

Via: Daily PTO Run
Sender's Initials: TJD/EP/kl

Date: February 25, 2004

02-25-04

1728254 v1: 111201!.DOC

Docket No.: M4065.0374/P374
(PATENT)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:
Mike Brooks

Application No.: 09/760,741 Art Unit: 2815

Filed: January 17, 2001 Examiner: C. C. Chu

For: SEMICONDUCTOR ASSEMBLY
WITHOUT ADHESIVE FILLETS

AMENDMENT IN RESPONSE TO NON-FINAL OFFICE ACTION

MS Non-Fee Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

INTRODUCTORY COMMENTS

In response to the Office Action dated December 30, 2003, please amend the above-identified U.S. patent application as follows:

Amendments to the Claims are reflected in the listing of claims which begins on page 2 of this paper.

Amendments to the Drawings begin on page 9 of this paper and include both an attached replacement sheet and an annotated sheet showing changes.

Amendments to the Specification begin on page 10 of this paper

Remarks begin on page 11 of this paper.

An **Appendix** including amended drawing figures is attached following page 23 of this paper.

AMENDMENTS TO THE SPECIFICATION

On page 9, please replace the last paragraph beginning on line 12, which extends to page 10, with the following:

Figure 7 is a cross-sectional illustration of a second exemplary embodiment of a semiconductor assembly 300 with second and third semiconductor dies 30, 45 secured to a first semiconductor die 20 using the techniques described above. As shown in Figure 7, when the adhesive fillet 24_b is eliminated, there can be cavities 25 between each of the second and third semiconductor dies 30, 45 and between the first semiconductor die 20 and the supporting structure 10. It is to be understood that the elimination of the adhesive fillet 24_b as discussed in Figure 1 covers a wide range of semiconductor configurations involving multiple dies with various sizes, dimensions, and electrical contact techniques. The above described invention has the advantage of allowing either the size of the second and third semiconductor dies 30, 45 to be increased or allowing the size of the first semiconductor die 20 to be reduced by eliminating the wasted space occupied by the adhesive fillet 24.

PTO/SB/44 (04-05)
Approved for use through 04/30/2007. OMB 0651-0033
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(Also Form PTO-1050)

UNITED STATES PATENT AND TRADEMARK OFFICE
CERTIFICATE OF CORRECTION

PATENT NO.	:	6,900,549
APPLICATION NO.	:	09/760,741
ISSUE DATE	:	May 31, 2005
INVENTOR	:	Jerry M. Brooks

It is certified that errors appear in the above-identified patent and that said Letters Patent is hereby corrected as shown below:

In the Specification, the following errors are corrected:

Column 1, line 31, "it Limits" should read --it limits--; and

Column 4, lines 17-18, "above. It" should read --above. As shown in Figure 7, when the adhesive fillet 24_b is eliminated, there can be cavities 25 between each of the second and third semiconductor dies 30, 45 and between the first semiconductor die 20 and the supporting structure 10. It--.

In Claim 9, the following is corrected:

Column 5, line 39, "arid" should read --and--.

MAILING ADDRESS OF SENDER (Please do not use customer number below):
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